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Details

Product Status	Obsolete
Core Processor	dsPIC
Core Size	16-Bit
Speed	60 MIPS
Connectivity	I ² C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	21
Program Memory Size	256KB (85.5K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 6x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 150°C (TA)
Mounting Type	Through Hole
Package / Case	28-DIP (0.300", 7.62mm)
Supplier Device Package	28-SPDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep256mc202-h-sp

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4.2 Data Address Space

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X CPU has a separate 16-bit-wide data memory space. The Data Space is accessed using separate Address Generation Units (AGUs) for read and write operations. The data memory maps, which are presented by device family and memory size, are shown in Figure 4-7 through Figure 4-16.

All Effective Addresses (EAs) in the data memory space are 16 bits wide and point to bytes within the Data Space. This arrangement gives a base Data Space address range of 64 Kbytes (32K words).

The base Data Space address is used in conjunction with a Read or Write Page register (DSRPAG or DSWPAG) to form an Extended Data Space, which has a total address range of 16 Mbytes.

dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices implement up to 52 Kbytes of data memory (4 Kbytes of data memory for Special Function Registers and up to 48 Kbytes of data memory for RAM). If an EA points to a location outside of this area, an all-zero word or byte is returned.

4.2.1 DATA SPACE WIDTH

The data memory space is organized in byte-addressable, 16-bit-wide blocks. Data is aligned in data memory and registers as 16-bit words, but all Data Space EAs resolve to bytes. The Least Significant Bytes (LSBs) of each word have even addresses, while the Most Significant Bytes (MSBs) have odd addresses.

4.2.2 DATA MEMORY ORGANIZATION AND ALIGNMENT

To maintain backward compatibility with PIC® MCU devices and improve Data Space memory usage efficiency, the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X instruction set supports both word and byte operations. As a consequence of byte accessibility, all Effective Address calculations are internally scaled to step through word-aligned memory. For example, the core recognizes that Post-Modified Register Indirect Addressing mode [Ws++] results in a value of Ws + 1 for byte operations and Ws + 2 for word operations.

A data byte read, reads the complete word that contains the byte, using the LSB of any EA to determine which byte to select. The selected byte is placed onto the LSB of the data path. That is, data memory and registers are organized as two parallel, byte-wide entities with shared (word) address decode but separate write lines. Data byte writes only write to the corresponding side of the array or register that matches the byte address.

All word accesses must be aligned to an even address. Misaligned word data fetches are not supported, so care must be taken when mixing byte and word operations, or translating from 8-bit MCU code. If a misaligned read or write is attempted, an address error trap is generated. If the error occurred on a read, the instruction underway is completed. If the error occurred on a write, the instruction is executed but the write does not occur. In either case, a trap is then executed, allowing the system and/or user application to examine the machine state prior to execution of the address Fault.

All byte loads into any W register are loaded into the LSB. The MSB is not modified.

A Sign-Extend (SE) instruction is provided to allow user applications to translate 8-bit signed data to 16-bit signed values. Alternatively, for 16-bit unsigned data, user applications can clear the MSB of any W register by executing a Zero-Extend (ZE) instruction on the appropriate address.

4.2.3 SFR SPACE

The first 4 Kbytes of the Near Data Space, from 0x0000 to 0x0FFF, is primarily occupied by Special Function Registers (SFRs). These are used by the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X core and peripheral modules for controlling the operation of the device.

SFRs are distributed among the modules that they control and are generally grouped together by module. Much of the SFR space contains unused addresses; these are read as '0'.

Note: The actual set of peripheral features and interrupts varies by the device. Refer to the corresponding device tables and pinout diagrams for device-specific information.

4.2.4 NEAR DATA SPACE

The 8-Kbyte area, between 0x0000 and 0x1FFF, is referred to as the Near Data Space. Locations in this space are directly addressable through a 13-bit absolute address field within all memory direct instructions. Additionally, the whole Data Space is addressable using MOV instructions, which support Memory Direct Addressing mode with a 16-bit address field, or by using Indirect Addressing mode using a working register as an Address Pointer.

5.2 RTSP Operation

RTSP allows the user application to erase a single page of memory and to program two instruction words at a time. See the General Purpose and Motor Control Family tables (Table 1 and Table 2, respectively) for the page sizes of each device.

For more information on erasing and programming Flash memory, refer to **"Flash Programming"** (DS70609) in the *"dsPIC33/PIC24 Family Reference Manual"*.

5.3 Programming Operations

A complete programming sequence is necessary for programming or erasing the internal Flash in RTSP mode. The processor stalls (waits) until the programming operation is finished.

For erase and program times, refer to Parameters D137a and D137b (Page Erase Time), and D138a and D138b (Word Write Cycle Time) in Table 30-14 in **Section 30.0 "Electrical Characteristics"**.

Setting the WR bit (NVMCON<15>) starts the operation and the WR bit is automatically cleared when the operation is finished.

5.3.1 PROGRAMMING ALGORITHM FOR FLASH PROGRAM MEMORY

Programmers can program two adjacent words (24 bits x 2) of program Flash memory at a time on every other word address boundary (0x000002, 0x000006, 0x00000A, etc.). To do this, it is necessary to erase the page that contains the desired address of the location the user wants to change.

For protection against accidental operations, the write initiate sequence for NVMKEY must be used to allow any erase or program operation to proceed. After the programming command has been executed, the user application must wait for the programming time until programming is complete. The two instructions following the start of the programming sequence should be NOPs.

Refer to **"Flash Programming"** (DS70609) in the *"dsPIC33/PIC24 Family Reference Manual"* for details and codes examples on programming using RTSP.

5.4 Flash Memory Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note: In the event you are not able to access the product page using the link above, enter this URL in your browser:
<http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en555464>

5.4.1 KEY RESOURCES

- **"Flash Programming"** (DS70609) in the *"dsPIC33/PIC24 Family Reference Manual"*
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related *"dsPIC33/PIC24 Family Reference Manual"* Sections
- Development Tools

5.5 Control Registers

Four SFRs are used to erase and write the program Flash memory: NVMCON, NVMKEY, NVMADRH and NVMADRL.

The NVMCON register (Register 5-1) enables and initiates Flash memory erase and write operations.

NVMKEY (Register 5-4) is a write-only register that is used for write protection. To start a programming or erase sequence, the user application must consecutively write 0x55 and 0xAA to the NVMKEY register.

There are two NVM Address registers: NVMADRH and NVMADRL. These two registers, when concatenated, form the 24-bit Effective Address (EA) of the selected word for programming operations or the selected page for erase operations.

The NVMADRH register is used to hold the upper 8 bits of the EA, while the NVMADRL register is used to hold the lower 16 bits of the EA.

7.3 Interrupt Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note: In the event you are not able to access the product page using the link above, enter this URL in your browser:
<http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en555464>

7.3.1 KEY RESOURCES

- “**Interrupts**” (DS70600) in the “*dsPIC33/PIC24 Family Reference Manual*”
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related “*dsPIC33/PIC24 Family Reference Manual*” Sections
- Development Tools

7.4 Interrupt Control and Status Registers

dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices implement the following registers for the interrupt controller:

- INTCON1
- INTCON2
- INTCON3
- INTCON4
- INTTREG

7.4.1 INTCON1 THROUGH INTCON4

Global interrupt control functions are controlled from INTCON1, INTCON2, INTCON3 and INTCON4.

INTCON1 contains the Interrupt Nesting Disable bit (NSTDIS), as well as the control and status flags for the processor trap sources.

The INTCON2 register controls external interrupt request signal behavior and also contains the Global Interrupt Enable bit (GIE).

INTCON3 contains the status flags for the DMA and D0 stack overflow status trap sources.

The INTCON4 register contains the software generated hard trap status bit (SGHT).

7.4.2 IFSx

The IFSx registers maintain all of the interrupt request flags. Each source of interrupt has a status bit, which is set by the respective peripherals or external signal and is cleared via software.

7.4.3 IECx

The IECx registers maintain all of the interrupt enable bits. These control bits are used to individually enable interrupts from the peripherals or external signals.

7.4.4 IPCx

The IPCx registers are used to set the Interrupt Priority Level (IPL) for each source of interrupt. Each user interrupt source can be assigned to one of eight priority levels.

7.4.5 INTTREG

The INTTREG register contains the associated interrupt vector number and the new CPU Interrupt Priority Level, which are latched into the Vector Number bits (VECNUM<7:0>) and Interrupt Priority Level bits (ILR<3:0>) fields in the INTTREG register. The new Interrupt Priority Level is the priority of the pending interrupt.

The interrupt sources are assigned to the IFSx, IECx and IPCx registers in the same sequence as they are listed in Table 7-1. For example, the INT0 (External Interrupt 0) is shown as having Vector Number 8 and a natural order priority of 0. Thus, the INT0IF bit is found in IFS0<0>, the INT0IE bit in IEC0<0> and the INT0IP bits in the first position of IPC0 (IPC0<2:0>).

7.4.6 STATUS/CONTROL REGISTERS

Although these registers are not specifically part of the interrupt control hardware, two of the CPU Control registers contain bits that control interrupt functionality. For more information on these registers refer to “**CPU**” (DS70359) in the “*dsPIC33/PIC24 Family Reference Manual*”.

- The CPU STATUS Register, SR, contains the IPL<2:0> bits (SR<7:5>). These bits indicate the current CPU Interrupt Priority Level. The user software can change the current CPU Interrupt Priority Level by writing to the IPLx bits.
- The CORCON register contains the IPL3 bit which, together with IPL<2:0>, also indicates the current CPU priority level. IPL3 is a read-only bit so that trap events cannot be masked by the user software.

All Interrupt registers are described in Register 7-3 through Register 7-7 in the following pages.

REGISTER 7-3: INTCON1: INTERRUPT CONTROL REGISTER 1

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
NSTDIS	OVAERR ⁽¹⁾	OVBERR ⁽¹⁾	COVAERR ⁽¹⁾	COVBERR ⁽¹⁾	OVATE ⁽¹⁾	OVBTE ⁽¹⁾	COVTE ⁽¹⁾
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0
SFTACERR ⁽¹⁾	DIV0ERR	DMACERR	MATHERR	ADDRERR	STKERR	OSCFail	—
bit 7							bit 0

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'
-n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

- bit 15 **NSTDIS:** Interrupt Nesting Disable bit
1 = Interrupt nesting is disabled
0 = Interrupt nesting is enabled
- bit 14 **OVAERR:** Accumulator A Overflow Trap Flag bit⁽¹⁾
1 = Trap was caused by overflow of Accumulator A
0 = Trap was not caused by overflow of Accumulator A
- bit 13 **OVBERR:** Accumulator B Overflow Trap Flag bit⁽¹⁾
1 = Trap was caused by overflow of Accumulator B
0 = Trap was not caused by overflow of Accumulator B
- bit 12 **COVAERR:** Accumulator A Catastrophic Overflow Trap Flag bit⁽¹⁾
1 = Trap was caused by catastrophic overflow of Accumulator A
0 = Trap was not caused by catastrophic overflow of Accumulator A
- bit 11 **COVBERR:** Accumulator B Catastrophic Overflow Trap Flag bit⁽¹⁾
1 = Trap was caused by catastrophic overflow of Accumulator B
0 = Trap was not caused by catastrophic overflow of Accumulator B
- bit 10 **OVATE:** Accumulator A Overflow Trap Enable bit⁽¹⁾
1 = Trap overflow of Accumulator A
0 = Trap is disabled
- bit 9 **OVBTE:** Accumulator B Overflow Trap Enable bit⁽¹⁾
1 = Trap overflow of Accumulator B
0 = Trap is disabled
- bit 8 **COVTE:** Catastrophic Overflow Trap Enable bit⁽¹⁾
1 = Trap on catastrophic overflow of Accumulator A or B is enabled
0 = Trap is disabled
- bit 7 **SFTACERR:** Shift Accumulator Error Status bit⁽¹⁾
1 = Math error trap was caused by an invalid accumulator shift
0 = Math error trap was not caused by an invalid accumulator shift
- bit 6 **DIV0ERR:** Divide-by-Zero Error Status bit
1 = Math error trap was caused by a divide-by-zero
0 = Math error trap was not caused by a divide-by-zero
- bit 5 **DMACERR:** DMAC Trap Flag bit
1 = DMAC trap has occurred
0 = DMAC trap has not occurred

Note 1: These bits are available on dsPIC33EPXXXMC20X/50X and dsPIC33EPXXXGP50X devices only.

8.0 DIRECT MEMORY ACCESS (DMA)

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to “**Direct Memory Access (DMA)**” (DS70348) in the “*dsPIC33/PIC24 Family Reference Manual*”, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 “Memory Organization”** in this data sheet for device-specific register and bit information.

The DMA Controller transfers data between Peripheral Data registers and Data Space SRAM

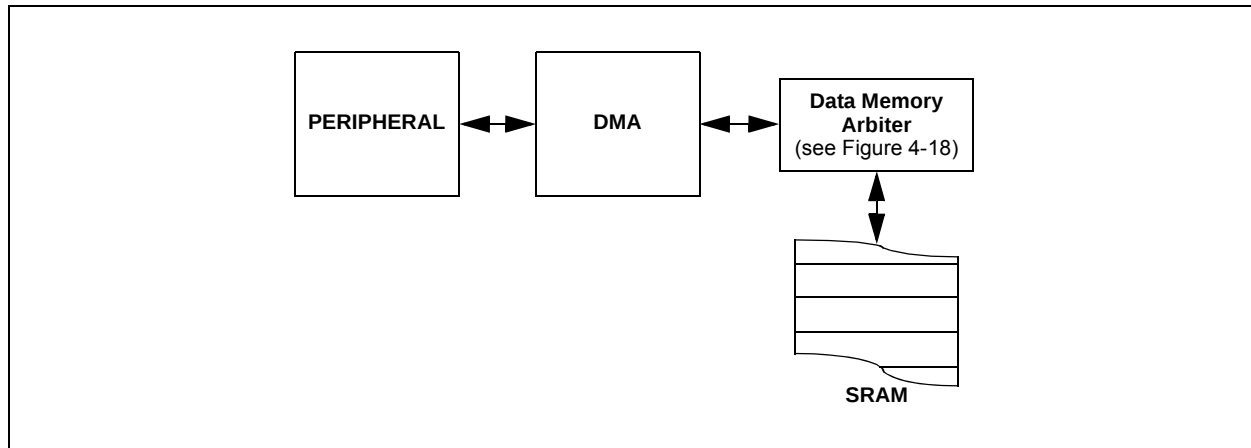
In addition, DMA can access the entire data memory space. The Data Memory Bus Arbiter is utilized when either the CPU or DMA attempts to access SRAM, resulting in potential DMA or CPU stalls.

The DMA Controller supports 4 independent channels. Each channel can be configured for transfers to or from selected peripherals. Some of the peripherals supported by the DMA Controller include:

- ECAN™
- Analog-to-Digital Converter (ADC)
- Serial Peripheral Interface (SPI)
- UART
- Input Capture
- Output Compare

Refer to Table 8-1 for a complete list of supported peripherals.

FIGURE 8-1: DMA CONTROLLER MODULE



13.2 Timer Control Registers

REGISTER 13-1: TxCON: (TIMER2 AND TIMER4) CONTROL REGISTER

R/W-0	U-0	R/W-0	U-0	U-0	U-0	U-0	U-0
TON	—	TSIDL	—	—	—	—	—
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0	U-0
—	TGATE	TCKPS1	TCKPS0	T32	—	TCS	—
bit 7							bit 0

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 15 **TON:** Timerx On bitWhen T32 = 1:

1 = Starts 32-bit Timerx/y

0 = Stops 32-bit Timerx/y

When T32 = 0:

1 = Starts 16-bit Timerx

0 = Stops 16-bit Timerx

bit 14 **Unimplemented:** Read as '0'bit 13 **TSIDL:** Timerx Stop in Idle Mode bit

1 = Discontinues module operation when device enters Idle mode

0 = Continues module operation in Idle mode

bit 12-7 **Unimplemented:** Read as '0'bit 6 **TGATE:** Timerx Gated Time Accumulation Enable bitWhen TCS = 1:

This bit is ignored.

When TCS = 0:

1 = Gated time accumulation is enabled

0 = Gated time accumulation is disabled

bit 5-4 **TCKPS<1:0>:** Timerx Input Clock Prescale Select bits

11 = 1:256

10 = 1:64

01 = 1:8

00 = 1:1

bit 3 **T32:** 32-Bit Timer Mode Select bit

1 = Timerx and Timery form a single 32-bit timer

0 = Timerx and Timery act as two 16-bit timers

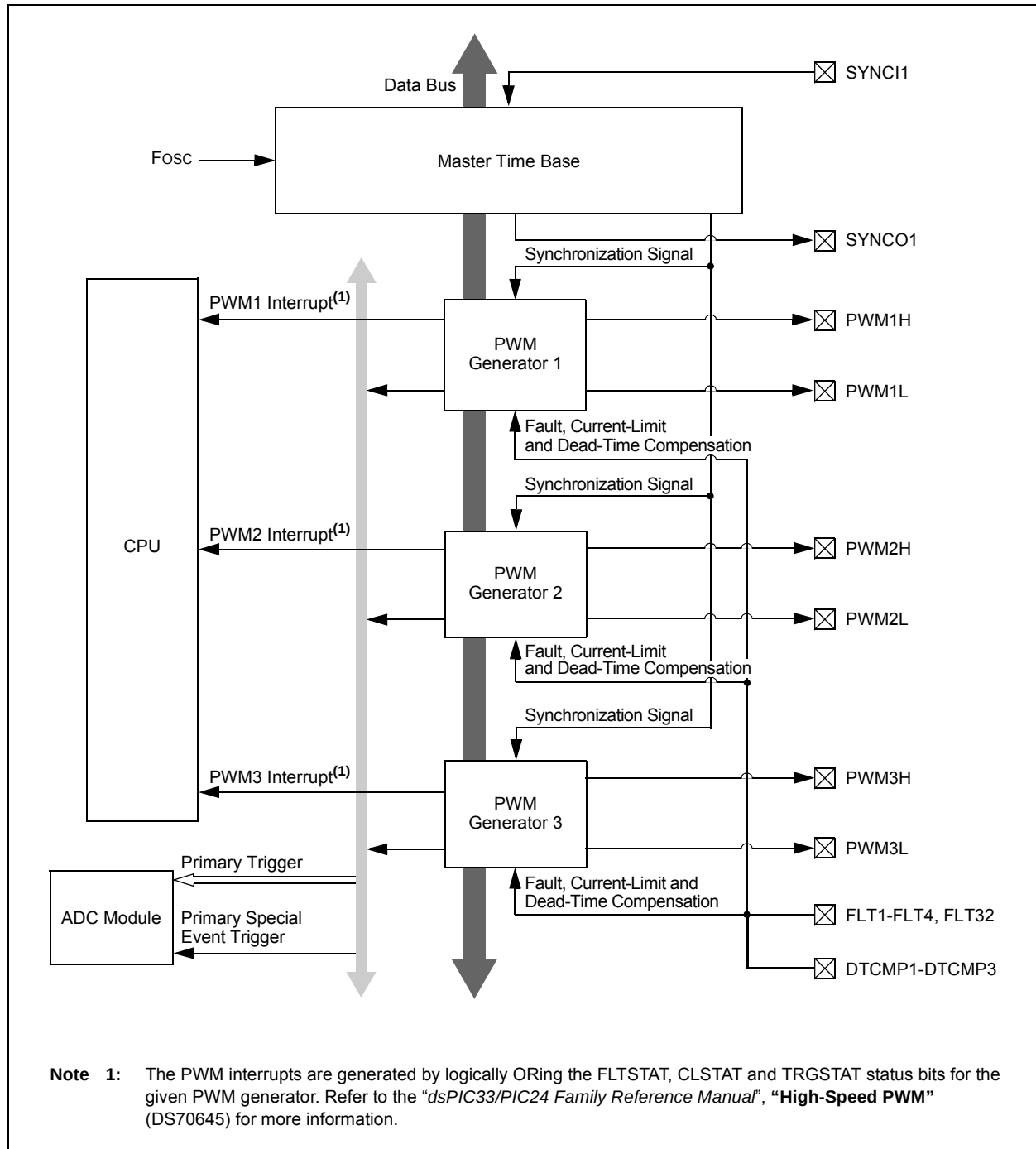
bit 2 **Unimplemented:** Read as '0'bit 1 **TCS:** Timerx Clock Source Select bit

1 = External clock is from pin, TxCK (on the rising edge)

0 = Internal clock (Fp)

bit 0 **Unimplemented:** Read as '0'

FIGURE 16-1: HIGH-SPEED PWMx MODULE ARCHITECTURAL OVERVIEW



21.0 ENHANCED CAN (ECAN™) MODULE (dsPIC33EPXXXGP/ MC50X DEVICES ONLY)

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to “**Enhanced Controller Area Network (ECAN™)**” (DS70353) in the “*dsPIC33/PIC24 Family Reference Manual*”, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 “Memory Organization”** in this data sheet for device-specific register and bit information.

21.1 Overview

The Enhanced Controller Area Network (ECAN) module is a serial interface, useful for communicating with other CAN modules or microcontroller devices. This interface/protocol was designed to allow communications within noisy environments. The dsPIC33EPXXXGP/MC50X devices contain one ECAN module.

The ECAN module is a communication controller implementing the CAN 2.0 A/B protocol, as defined in the BOSCH CAN specification. The module supports CAN 1.2, CAN 2.0A, CAN 2.0B Passive and CAN 2.0B Active versions of the protocol. The module implementation is a full CAN system. The CAN specification is not covered within this data sheet. The reader can refer to the BOSCH CAN specification for further details.

The ECAN module features are as follows:

- Implementation of the CAN protocol, CAN 1.2, CAN 2.0A and CAN 2.0B
- Standard and extended data frames
- 0-8 bytes data length
- Programmable bit rate up to 1 Mbit/sec
- Automatic response to remote transmission requests
- Up to eight transmit buffers with application specified prioritization and abort capability (each buffer can contain up to 8 bytes of data)
- Up to 32 receive buffers (each buffer can contain up to 8 bytes of data)
- Up to 16 full (Standard/Extended Identifier) acceptance filters
- Three full acceptance filter masks
- DeviceNet™ addressing support
- Programmable wake-up functionality with integrated low-pass filter
- Programmable Loopback mode supports self-test operation
- Signaling via interrupt capabilities for all CAN receiver and transmitter error states
- Programmable clock source
- Programmable link to Input Capture (IC2) module for time-stamping and network synchronization
- Low-power Sleep and Idle mode

The CAN bus module consists of a protocol engine and message buffering/control. The CAN protocol engine handles all functions for receiving and transmitting messages on the CAN bus. Messages are transmitted by first loading the appropriate data registers. Status and errors can be checked by reading the appropriate registers. Any message detected on the CAN bus is checked for errors and then matched against filters to see if it should be received and stored in one of the receive registers.

NOTES:

REGISTER 24-1: PTGCST: PTG CONTROL/STATUS REGISTER (CONTINUED)

bit 1-0 **PTGITM<1:0>**: PTG Input Trigger Command Operating Mode bits⁽¹⁾
11 = Single level detect with Step delay not executed on exit of command (regardless of the PTGCTRL command)
10 = Single level detect with Step delay executed on exit of command
01 = Continuous edge detect with Step delay not executed on exit of command (regardless of the PTGCTRL command)
00 = Continuous edge detect with Step delay executed on exit of command

- Note 1:** These bits apply to the PTGWHI and PTGWLO commands only.
2: This bit is only used with the PTGCTRL step command software trigger option.
3: Use of the PTG Single-Step mode is reserved for debugging tools only.

REGISTER 24-4: PTGT0LIM: PTG TIMER0 LIMIT REGISTER⁽¹⁾

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PTGT0LIM<15:8>							
bit 15				bit 8			

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PTGT0LIM<7:0>							
bit 7				bit 0			

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 15-0 **PTGT0LIM<15:0>**: PTG Timer0 Limit Register bits
General Purpose Timer0 Limit register (effective only with a PTGT0 Step command).

Note 1: This register is read-only when the PTG module is executing Step commands (PTGEN = 1 and PTGSTRT = 1).

REGISTER 24-5: PTGT1LIM: PTG TIMER1 LIMIT REGISTER⁽¹⁾

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PTGT1LIM<15:8>							
bit 15				bit 8			

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PTGT1LIM<7:0>							
bit 7				bit 0			

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 15-0 **PTGT1LIM<15:0>**: PTG Timer1 Limit Register bits
General Purpose Timer1 Limit register (effective only with a PTGT1 Step command).

Note 1: This register is read-only when the PTG module is executing Step commands (PTGEN = 1 and PTGSTRT = 1).

NOTES:

REGISTER 25-2: CMxCON: COMPARATOR x CONTROL REGISTER (x = 1, 2 OR 3)

R/W-0	R/W-0	R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0
CON	COE ⁽²⁾	CPOL	—	—	OPMODE	CEVT	COUT
bit 15							bit 8

R/W-0	R/W-0	U-0	R/W-0	U-0	U-0	R/W-0	R/W-0
EVPOL1	EVPOL0	—	CREF ⁽¹⁾	—	—	CCH1 ⁽¹⁾	CCH0 ⁽¹⁾
bit 7							bit 0

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

- bit 15 **CON:** Op Amp/Comparator Enable bit
1 = Op amp/comparator is enabled
0 = Op amp/comparator is disabled
- bit 14 **COE:** Comparator Output Enable bit⁽²⁾
1 = Comparator output is present on the CxOUT pin
0 = Comparator output is internal only
- bit 13 **CPOL:** Comparator Output Polarity Select bit
1 = Comparator output is inverted
0 = Comparator output is not inverted
- bit 12-11 **Unimplemented:** Read as '0'
- bit 10 **OPMODE:** Op Amp/Comparator Operation Mode Select bit
1 = Circuit operates as an op amp
0 = Circuit operates as a comparator
- bit 9 **CEVT:** Comparator Event bit
1 = Comparator event according to the EVPOL<1:0> settings occurred; disables future triggers and interrupts until the bit is cleared
0 = Comparator event did not occur
- bit 8 **COUT:** Comparator Output bit
When CPOL = 0 (non-inverted polarity):
1 = VIN+ > VIN-
0 = VIN+ < VIN-
When CPOL = 1 (inverted polarity):
1 = VIN+ < VIN-
0 = VIN+ > VIN-

Note 1: Inputs that are selected and not available will be tied to Vss. See the “Pin Diagrams” section for available inputs for each package.

2: This output is not available when OPMODE (CMxCON<10>) = 1.

29.11 Demonstration/Development Boards, Evaluation Kits and Starter Kits

A wide variety of demonstration, development and evaluation boards for various PIC MCUs and dsPIC DSCs allows quick application development on fully functional systems. Most boards include prototyping areas for adding custom circuitry and provide application firmware and source code for examination and modification.

The boards support a variety of features, including LEDs, temperature sensors, switches, speakers, RS-232 interfaces, LCD displays, potentiometers and additional EEPROM memory.

The demonstration and development boards can be used in teaching environments, for prototyping custom circuits and for learning about various microcontroller applications.

In addition to the PICDEM™ and dsPICDEM™ demonstration/development board series of circuits, Microchip has a line of evaluation kits and demonstration software for analog filter design, KEELOQ® security ICs, CAN, IrDA®, PowerSmart battery management, SEEVAL® evaluation system, Sigma-Delta ADC, flow rate sensing, plus many more.

Also available are starter kits that contain everything needed to experience the specified device. This usually includes a single application and debug capability, all on one board.

Check the Microchip web page (www.microchip.com) for the complete list of demonstration, development and evaluation kits.

29.12 Third-Party Development Tools

Microchip also offers a great collection of tools from third-party vendors. These tools are carefully selected to offer good value and unique functionality.

- Device Programmers and Gang Programmers from companies, such as SoftLog and CCS
- Software Tools from companies, such as Gimpel and Trace Systems
- Protocol Analyzers from companies, such as Saleae and Total Phase
- Demonstration Boards from companies, such as MikroElektronika, Digilent® and Olimex
- Embedded Ethernet Solutions from companies, such as EZ Web Lynx, WIZnet and IPLogika®

TABLE 30-4: DC TEMPERATURE AND VOLTAGE SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions (see Note 1): 3.0V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for Extended				
Param No.	Symbol	Characteristic	Min.	Typ.	Max.	Units	Conditions
Operating Voltage							
DC10	VDD	Supply Voltage	3.0	—	3.6	V	
DC16	VPOR	VDD Start Voltage to Ensure Internal Power-on Reset Signal	—	—	VSS	V	
DC17	SVDD	VDD Rise Rate to Ensure Internal Power-on Reset Signal	0.03	—	—	V/ms	0V-1V in 100 ms

Note 1: Device is functional at $V_{BORMIN} < V_{DD} < V_{DDMIN}$. Analog modules (ADC, op amp/comparator and comparator voltage reference) may have degraded performance. Device functionality is tested but not characterized. Refer to Parameter BO10 in Table 30-13 for the minimum and maximum BOR values.

TABLE 30-5: FILTER CAPACITOR (CEFC) SPECIFICATIONS

Standard Operating Conditions (unless otherwise stated): Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for Extended							
Param No.	Symbol	Characteristics	Min.	Typ.	Max.	Units	Comments
	CEFC	External Filter Capacitor Value ⁽¹⁾	4.7	10	—	μF	Capacitor must have a low series resistance (< 1 Ohm)

Note 1: Typical VCAP voltage = 1.8 volts when $V_{DD} \geq V_{DDMIN}$.

31.1 High-Temperature DC Characteristics

TABLE 31-1: OPERATING MIPS VS. VOLTAGE

Characteristic	VDD Range (in Volts)	Temperature Range (in °C)	Max MIPS
			dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X
HDC5	3.0 to 3.6V ⁽¹⁾	-40°C to +150°C	40

Note 1: Device is functional at $V_{BORMIN} < V_{DD} < V_{DDMIN}$. Analog modules, such as the ADC, may have degraded performance. Device functionality is tested but not characterized.

TABLE 31-2: THERMAL OPERATING CONDITIONS

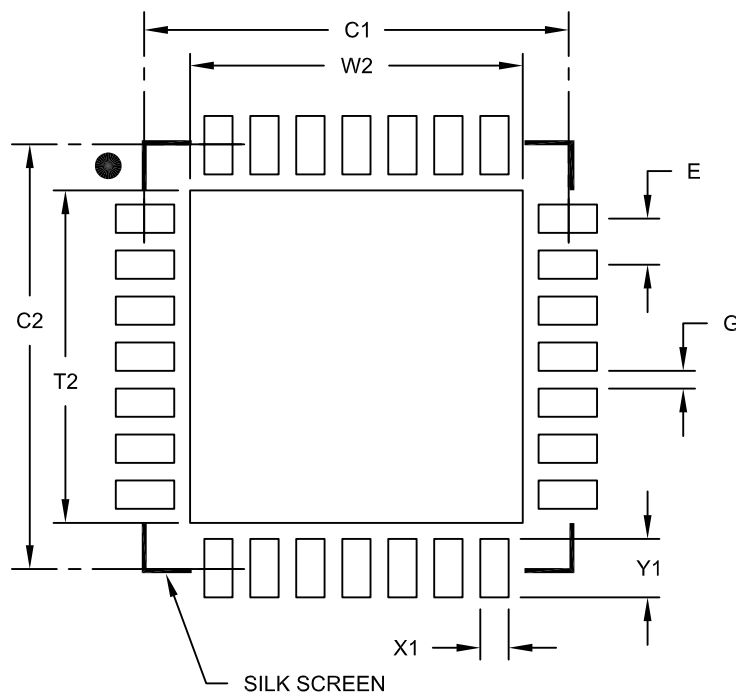
Rating	Symbol	Min	Typ	Max	Unit
High-Temperature Devices					
Operating Junction Temperature Range	TJ	-40	—	+155	°C
Operating Ambient Temperature Range	TA	-40	—	+150	°C
Power Dissipation: Internal Chip Power Dissipation: $P_{INT} = V_{DD} \times (I_{DD} - \sum I_{OH})$ I/O Pin Power Dissipation: $I/O = \sum (\{V_{DD} - V_{OH}\} \times I_{OH}) + \sum (V_{OL} \times I_{OL})$	PD	PINT + PI/O			W
Maximum Allowed Power Dissipation	PDMAX	$(T_J - T_A)/\theta_{JA}$			W

TABLE 31-3: DC TEMPERATURE AND VOLTAGE SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature $-40^\circ\text{C} \leq T_A \leq +150^\circ\text{C}$				
Parameter No.	Symbol	Characteristic	Min	Typ	Max	Units	Conditions
Operating Voltage							
HDC10	Supply Voltage						
	VDD	—	3.0	3.3	3.6	V	-40°C to +150°C

**28-Lead Plastic Quad Flat, No Lead Package (MM) – 6x6x0.9 mm Body [QFN-S]
with 0.40 mm Contact Length**

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Contact Pitch	E	0.65 BSC		
Optional Center Pad Width	W2			4.70
Optional Center Pad Length	T2			4.70
Contact Pad Spacing	C1		6.00	
Contact Pad Spacing	C2		6.00	
Contact Pad Width (X28)	X1			0.40
Contact Pad Length (Y28)	Y1			0.85
Distance Between Pads	G	0.25		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2124A

48-Lead Plastic Ultra Thin Quad Flat, No Lead Package (MV) – 6x6x0.5 mm Body [UQFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>

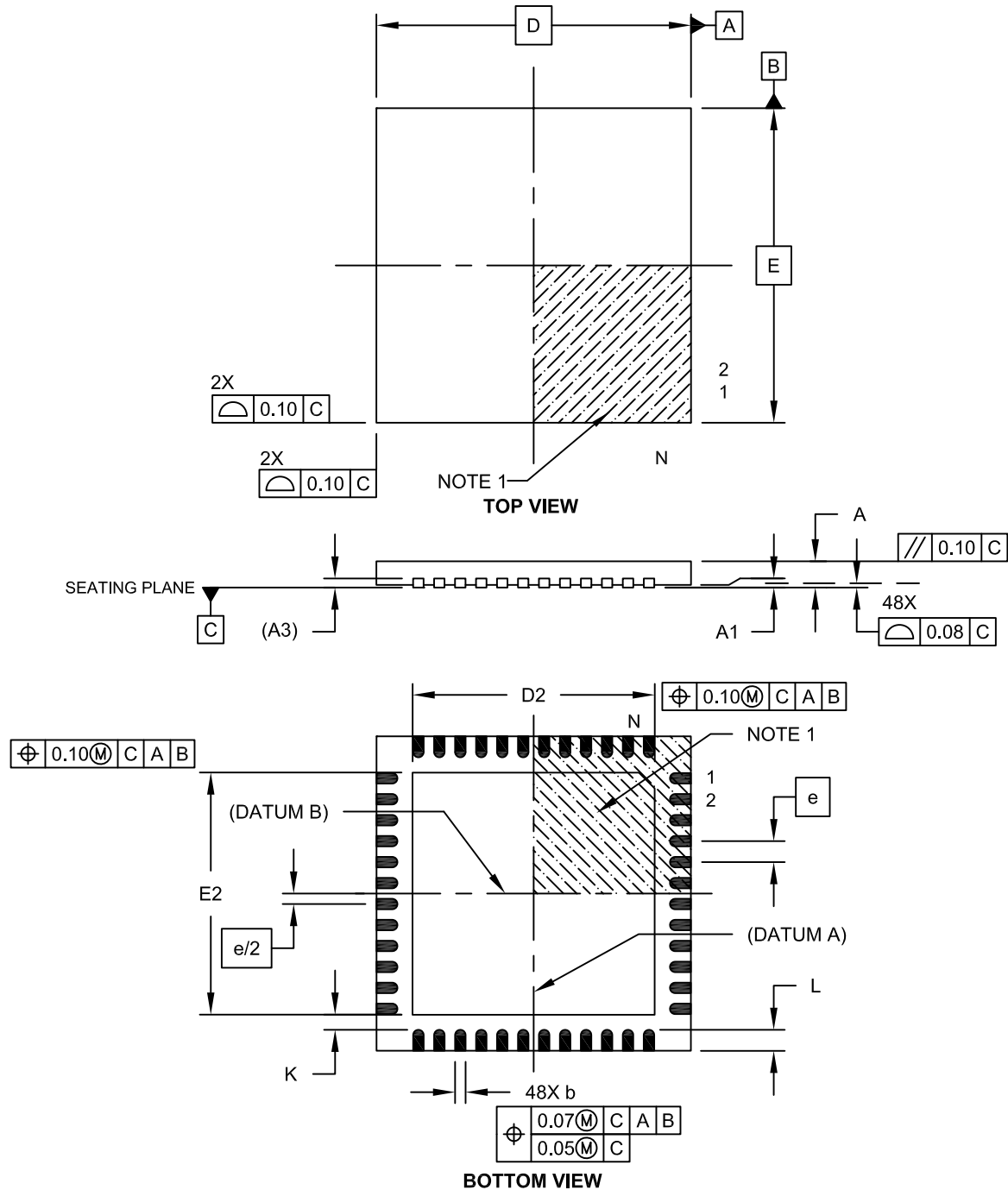


TABLE A-1: MAJOR SECTION UPDATES (CONTINUED)

Section Name	Update Description
Section 30.0 “Electrical Characteristics”	Removed Voltage on VCAP with respect to Vss and added Note 5 in Absolute Maximum Ratings⁽¹⁾. Removed Parameter DC18 (V_{CORE}) and Note 3 from the DC Temperature and Voltage Specifications (see Table 30-4). Updated Note 1 in the DC Characteristics: Operating Current (I_{DD}) (see Table 30-6). Updated Note 1 in the DC Characteristics: Idle Current (I_{IDLE}) (see Table 30-7). Changed the Typical values for Parameters DC60a-DC60d and updated Note 1 in the DC Characteristics: Power-down Current (I_{PD}) (see Table 30-8). Updated Note 1 in the DC Characteristics: Doze Current (I_{DOZE}) (see Table 30-9). Updated Note 2 in the Electrical Characteristics: BOR (see Table 30-12). Updated Parameters CM20 and CM31, and added Parameters CM44 and CM45 in the AC/DC Characteristics: Op amp/Comparator (see Table 30-14). Added the Op amp/Comparator Reference Voltage Settling Time Specifications (see Table 30-15). Added Op amp/Comparator Voltage Reference DC Specifications (see Table 30-16). Updated Internal FRC Accuracy Parameter F20a (see Table 30-21). Updated the Typical value and Units for Parameter CTMUI1, and added Parameters CTMUI4, CTMUFV1, and CTMUFV2 to the CTMU Current Source Specifications (see Table 30-55).
Section 31.0 “Packaging Information”	Updated packages by replacing references of VLAP with TLA.
“Product Identification System”	Changed VLAP to TLA.